BERGQUIST



BERGQUIST GAP PAD® TGP 10000ULM

HIGH-COMPLIANCE, LOW COMPRESSION STRESS, ULTRA-LOW MODULUS GAP PAD®

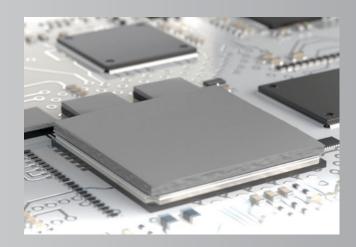
Henkel's BERGQUIST GAP PAD® TGP 10000ULM unites very high thermal conductivity and ultra-low modulus to address the demands of next-generation telecom and datacom applications. With power densities and thermal loads increasing while devices continue to reduce in footprint, heat dissipation in combination with low assembly stress is required for optimal performance and reliability. BERGQUIST GAP PAD TGP 10000ULM is a soft, conforming pad that provides excellent wet out at the interface even on rough or irregular surfaces, delivering optimized thermal transfer and minimizing assembly stress. Formulated on a silicone-based resin platform, the materials are supplied in pre-cut pads with tack on both sides for easy application.





Key Benefits

- Low assembly stress due to ultra-low modulus of 75 hardness (Shore 000, ASTM D2240) and 173 Young's Modulus (kPa, ASTM D575)
- Excellent conformability to rough or irregular surfaces
- Thorough wet out at the interface for maximized thermal transfer
- High thermal conductivity of 10.0 W/m-K (ASTM D5470)
- Simplified application and processability; supplied in precut, custom-sized pads with high tack on both sides
- Ability to use a single pad for multi-height chips and/or multiple devices
- Room temperature storage



PRODUCT PROPERTIES	BERGQUIST GAP PAD® TGP 10000ULM
Hardness (Shore 000)	75
Inherent Surface Tack	2
Thermal Conductivity (W/m-K)	10
Young's Modulus (kPa)	173
Dielectric Breakdown Voltage: 40 mil sample (VAC)	3,200
Appearance	Gray

Typical applications

- Telecommunications (routers, switches and base stations)
- Optical Transceivers
- ASICs and DSPs





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